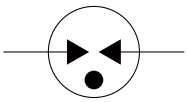
FEATURES

- Surface Mounting Design 6.2*6.2*4.2mm
- High Current Handling Capability 5000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level：Level 1

6.2*6.2*4.2mm



Schematic Symbol

APPLICATION INFORMATION

- Communication equipment.
- Repeaters,Modems
- Telephone Interface,Line cards.
- Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	640-960	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ⩽ 1400	V
	At 1kV/μs	Typical values of distribution ⩽ 1350	V
Impulse Discharge Current 2)	8/20μs	5000	A
AC Discharge Current	50Hz, 1S, 10times	5	A
Insulation Resistance	DC=100V	⩾ 1	GΩ
Capacitance at 1MHz	V_{DC}=0.5V	⩽ 1	pF
Operating And Storage Temperature		-40-125	°C

1) In ionized mode
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

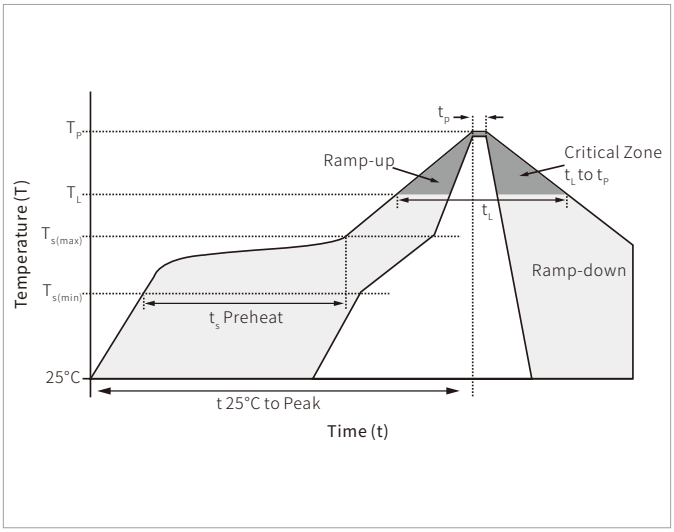
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude：0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering：10s，1time

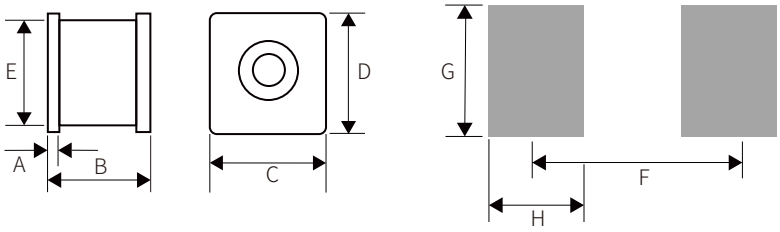
NOTE: Up-screen program can be specified by customer' s request via contacting Semiware service

SOLDERING PARAMETERS

Reflow Condition		Lead–free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

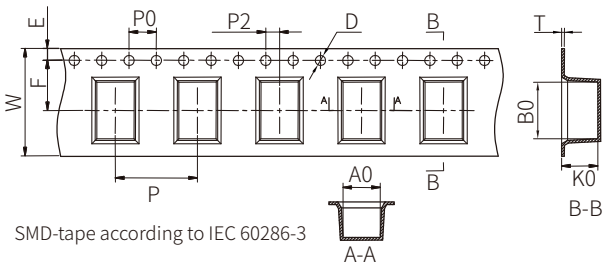


DIMENSIONS AND RECOMMENDED SOLDERING PAD

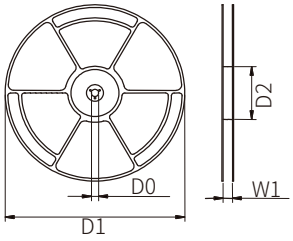


Ref.	mm
A	0.6±0.1
B	4.2±0.3
C	6.2±0.2
D	6.2±0.2
E	Φ6±0.1
F	3.5
G	6.8
H	1.2

TAPE AND REEL SPECIFICATION



SMD-tape according to IEC 60286-3



Ref.	Dimensions	
	Millimeters	Inches
W	16±0.3	0.630±0.012
A0	4.6±0.1	0.181±0.004
B0	6.5±0.1	0.256±0.004
K0	6.7±0.1	0.264±0.004
P	12±0.1	0.472±0.004
F	7.5±0.1	0.295±0.004
E	1.75±0.1	0.069±0.004
D	1.5+0.1/-0.0	0.059+0.004/-0.0
P0	4±0.1	0.157±0.004
P2	2±0.1	0.079±0.004
T	0.5±0.1	0.020±0.004
D0	13.3±0.15	0.524±0.006
D1	330±2	12.992±0.079
D2	100+1/-2	3.937+0.039/-0.079
W1	16.5±0.4	0.65±0.016

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R06B800A	6.2*6.2*4.2mm	SG800 06	800PCS	13”

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